

ABSTRACT

There is provided a photocurable and thermosetting resin composition which suppresses decrease of adhesive strength in a moisture resistance test of the cured resin composition, and has a sufficiently long pot life. The resin composition includes (A) an acrylic resin, (B) a multifunctional nitrogen-containing heterocyclic compound represented by a specific chemical formula, (C) a latent curing agent, (D) a radical polymerization inhibitor, and (E) an anionic polymerization retarder. The resin composition preferably further includes (F) a compound having a glycidyl group, other than the acrylic resin.